

# Multilayer Ceramic Chip Capacitors

## C3225X7R1N106K250AC



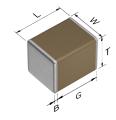






#### **TDK item description** C3225X7R1N106KT\*\*\*\*

Applications	Commercial Grade  Please refer to Part No. CGA6P1X7R1N106K250AC for Automotive use.	
Feature	General General (Up to 75V)	
Series	C3225 [EIA 1210]	
Status	Production	



9	iize
Length(L)	3.20mm ±0.40mm
Width(W)	2.50mm ±0.30mm
Thickness(T)	2.50mm ±0.30mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	
Recommended Land Pattern (PA)	2.00mm to 2.40mm
Recommended Land Pattern (PB)	1.00mm to 1.20mm
Recommended Land Pattern (PC)	1.90mm to 2.50mm

Electrical Characteristics		
Capacitance	10μF ±10%	
Rated Voltage	75VDC	
Temperature Characteristic	X7R(±15%)	
Dissipation Factor (Max.)	5%	
Insulation Resistance (Min.)	50ΜΩ	

Other		
Soldering Method	Reflow	
AEC-Q200	No	
Packing	Blister (Plastic)Taping [180mm Reel]	
Package Quantity	1000pcs	

<sup>!</sup> Images are for reference only and show exemplary products.

<sup>!</sup> This PDF document was created based on the data listed on the TDK Corporation website.

<sup>!</sup> All specifications are subject to change without notice.

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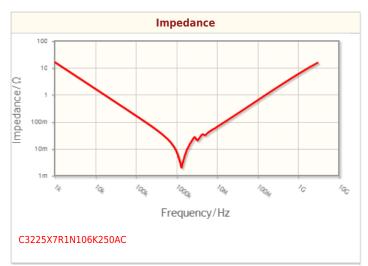


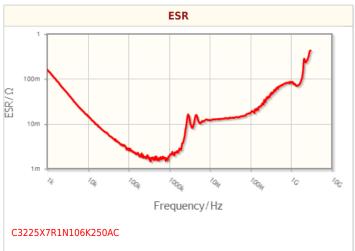


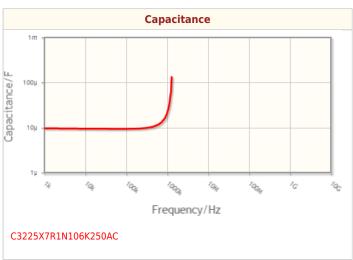


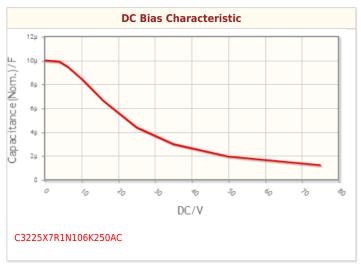


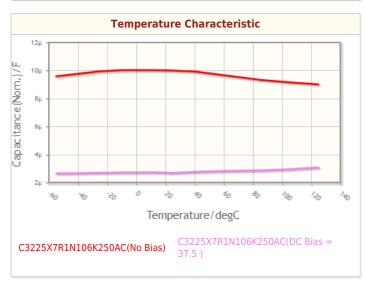
# Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

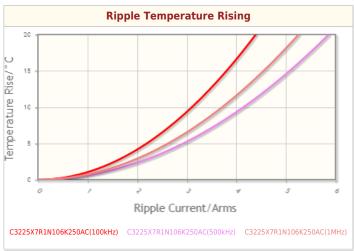












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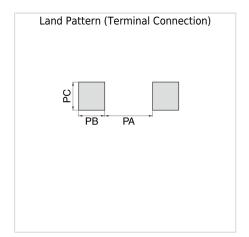








# **Associated Images**



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